2SC3825

Silicon PNP Triple-Diffused Planar Type

High Breakdown Voltage, High Speed Switching

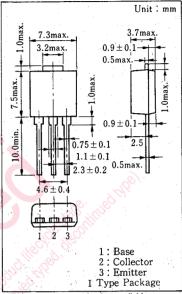
■ Features

- High speed switching
- Low collector-emitter saturation voltage (VCE (sat))
- "I Type" package configuration with a cooling fin for direct soldering on PC board of a small-size electronic equipment

■ Absolute Maximum Ratings (Tc=25°C)

Item		Symbol	Value	Unit	
Collector-base voltage		V _{CBO}	500	V	
Collector-emitter voltage		V _{CEO}	400	V	
Emitter-base voltage		V _{EBO}	7	V	
Peak collector current		I _{CP}	4	A	
Collector current		Ic	2	A	
Collector power dissipation	Tc=25 ℃	n	15	117	
	Ta=25 ℃	P_{C}	1.3	W	
Junction temperature		T_{i}	150	${\mathfrak C}$	
Storage temperature		Tstg	$-55 \sim +150$	С.	

■ Package Dimensions

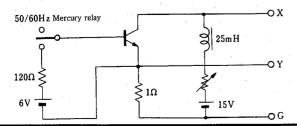


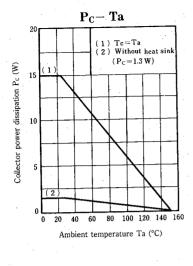
*Surface-mount type is also available. (Refer to p.81.)

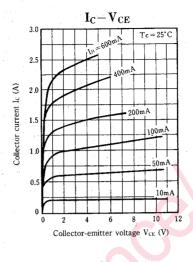
■ Electrical Characteristics (Tc=25°C)

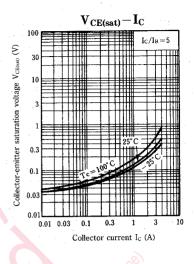
Item	Symbol	Condition	min.	typ.	max.	Unit
Collector cutoff current	Ісво	$V_{CB} = 500 \text{ V}, I_E = 0$		-	100	μA
Emitter cutoff current	I_{EBO}	$V_{EB}=5$ V, $I_C=0$	1.4		100	μA
Collector-emitter voltage	V _{CEO(sus)}	$I_{C}=0.2 \text{ A}, L=25 \text{ mH}$	400	-		. V
DC	h _{FE1}	$V_{CE} = 5 \text{ V}, I_{C} = 0.1 \text{ A}$	15			
DC current gain	h _{FE2}	$V_{CE}=5 V$, $I_C=1 A$	8			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 1 \text{ A}, I_B = 0.2 \text{ A}$			1	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_{C}=1 \text{ A}, I_{B}=0.2 \text{ A}$			1.5	V
Transition frequency	fr	$V_{CE} = 10V, I_{C} = 0.2A, f = 1MHz$		8		MHz
Turn-on time	ton Con	I _C =1 A	-		1	μS
Storage time t _{stg}		$I_{B1} = 0.2 \text{ A}, I_{B2} = -0.2 \text{ A}$			3	μS
Collector current fall time	tr	V _{CC} =100 V			1	μS

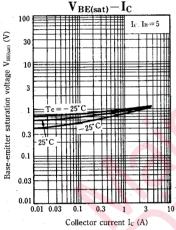
* V_{CEO (sus)} Test method

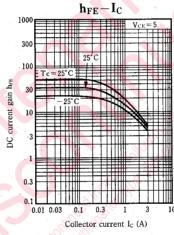


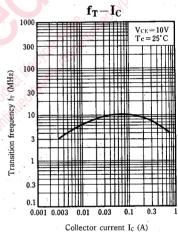


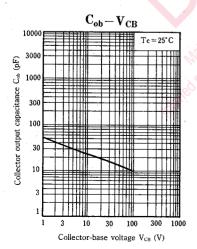


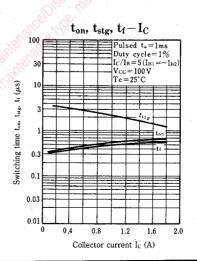


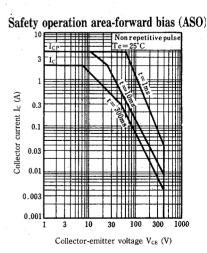






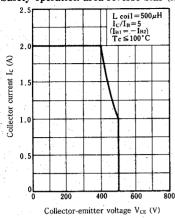


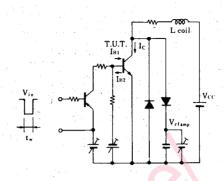


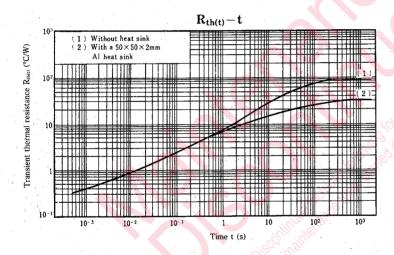


Safety operation area-reverse bias (ASO)

Measurement circuit of reverse bias ASO







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